IN THE CLAIMS:

Please amend claims 1, 10 and 23 as follows. This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): A printed wiring board with an electronic component mounted on a circuit board in which the electronic component is provided with a heat radiating plate for conducting heat internally generated, comprising:

a first heat radiating pattern for conducting heat which is formed on a front surface of said circuit board, and connected to said heat radiating plate of the electronic component by soldering;

a second heat radiating pattern for conducting heat which is formed on a rear surface of said circuit board at a position being opposed to said electronic component, and

heat radiating means mounted on said second heat radiating pattern by soldering at a position being opposed to the electronic component, wherein

said heat radiating plate and said first radiating pattern have a same area whereas said second heat radiating pattern has a larger area than that of said first radiating pattern or said heat radiating plate, wherein said heat radiating means is made of metal, and is provided, on a rear side thereof, with a plated layer which is able to be brought into contact with said circuit board and on a front side thereof, with a plurality of fins for radiating heat, wherein said plurality of fins for radiating heat forms a corrugated cross-section being uniformly shaped in such a way that a long-length of a belt-shaped hoop material is extruded and cut at prescribed length, and

wherein said second heat radiating pattern is formed apart from the electronic component on the rear surface of said circuit board and serves as a grounding electrode for the electronic component.

Claim 2-9 (Canceled).

Claim 10 (Previously Presented): The printed wiring board according to claim 1, wherein said first heat radiating pattern and said second heat radiating pattern are connected to each other via through-holes which pass through said circuit board.

Claim 11 (Previously Presented): The printed wiring board according to claim 1, wherein said first heat radiating pattern is a common pattern of wiring patterns which constitute circuits formed on said circuit board.

Claim 12 (Previously Presented): The printed wiring board according to claim 1, wherein said second heat radiating pattern is a common pattern of wiring patterns which constitute circuits formed on said circuit board.

Claims 13 and 14 (Canceled).

Claim 15 (Currently Amended): A printed wiring board, comprising:

a circuit board;

an electronic component mounted on said circuit board and including a heat radiating plate for conducting heat internally generated;

a first heat radiating pattern for conducting heat formed at a position on a front surface of said circuit board corresponding to said electronic component, such that the heat radiating plate of said electronic component is connected to said first heat radiating pattern by soldering;

a second heat radiating pattern for conducting heat formed at a position on a rear surface of said circuit board corresponding to said electronic component;

a plated layer to which said second heat radiating pattern is soldered; and

heat radiating means mounted at a position corresponding to said electronic component on the rear surface of said circuit board, such that said heat radiating means is mounted on said circuit board via said plated layer, wherein

said second heat radiating pattern has a larger area than that of said first heat radiating pattern, wherein said heat radiating means is made of metal, and is provided, on a rear side thereof, with a plated layer which is able to be brought into contact with said circuit board and on a front side thereof, with a plurality of fins for radiating heat, wherein said plurality of fins for radiating heat forms a corrugated cross-section being uniformly shaped in such a way that a long-length of a belt-shaped hoop material is extruded and cut at prescribed length, and wherein said second heat radiating pattern is formed apart from the electronic component on the rear surface of said circuit board and serves as a grounding electrode for the electronic component.

Claim 16 (Original): The printed wiring board according to claim 15, wherein said plated layer contains tin.

Claim 17 (Original): The printed wiring board according to claim 15, wherein said plated layer contains nickel.

Claim 18 (Original): The printed wiring board according to claim 15, wherein said plated layer includes a first layer containing nickel and a second layer containing tin.

Claim 19 (Canceled).

Claim 20 (Original): The printed wiring board according to claim 15, wherein said first heat radiating pattern is a common pattern of wiring patterns which constitute circuits formed on said circuit board.

Claim 21 (Original): The printed wiring board according to claim 15, wherein said second heat radiating pattern is a common pattern of wiring patterns which constitute circuits formed on said circuit board.

Claim 22 (Original): The printed wiring board according to claim 15, wherein said first heat radiating pattern and said second heat radiating pattern are connected via at least one through hole in heat, and an inner surface of the through hole is covered with a material having a specific heat smaller than that of the printed wiring board.

Claim 23 (Currently Amended): A printed wiring board with an electronic component mounted on a circuit board in which the electronic component is provided with a heat radiating plate for conducting heat internally generated, comprising:

a first heat radiating pattern for conducting heat which is formed on a front surface of said circuit board, and connected to said heat radiating plate of the electronic component by soldering;

a second heat radiating pattern for conducting heat which is formed on a rear surface of said circuit board at a position being opposed to said electronic component, and

heat radiating means mounted on said second heat radiating pattern by soldering at a position being opposed to the electronic component, wherein

said heat radiating plate and said first heat radiating pattern have a same area whereas said second heat radiating pattern has a larger area than that of said first heat radiating pattern or said heat radiating plate, and wherein said second heat radiating pattern is formed apart from the electronic component on the rear surface of said circuit board and serves as a grounding electrode for the electronic component.

Claim 24 (Previously Presented): The printed wiring board according to claim 23, wherein said heat radiating means is made of metal, and is provided, on a rear side thereof, with a plated layer which is able to be brought into contact with said circuit board and on a front side thereof, with a plurality of fins for radiating heat.

Claim 25 (Previously Presented): The printed wiring board according to claim 24, wherein said plurality of fins for radiating heat forms a corrugated cross-section being uniformly shaped in such a way that a long-length of a belt-shaped hoop material is extruded and cut at prescribed length.

Claim 26 (Previously Presented): The printed wiring board according to claim 23, wherein said first heat radiating pattern and said second heat radiating pattern are connected to each other via through-holes which pass through said circuit board.

Claim 27 (Previously Presented): The printed wiring board according to claim 23, wherein said first heat radiating pattern is a common pattern of wiring patterns which constitute circuits formed on said circuit board.

Claim 28 (Previously Presented): The printed wiring board according to claim 23, wherein said second heat radiating pattern is a common pattern of wiring patterns which constitute circuits formed on said circuit board.

Claim 29 (Previously Presented): The printed wiring board according to claim 24, wherein said fins of said heat radiating means are designed to stand with respect to the circuit board.